

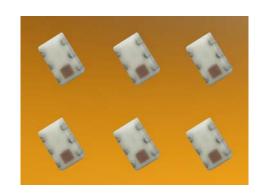
BL 1608 Series Multilayer Chip Baluns

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖RoHS compliant

Applications

•0.6 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, Hyper-LAN, etc.



Specifications

Part Number	Frequency Range (MHz)	Unbalanced Impedance (ohm)	Balanced Impedance (ohm)	Insertion Loss (dB)	VSWR @BW		Amplitude Difference (dB)
BL1608- 10V4600KB_	3200 ~ 6000	50	100	0.7typ. / 1.2 max. @-40~85°C 1.05 typ. / 1.4 max @105°C	1.7typ. / 2.3 max.	180 ± 15	2.0 max.

Q'ty/Reel (pcs) : 4000

Operating Temperature Range : $-40 \sim +105^{\circ}$ C Storage Temperature Range : $-40 \sim +105^{\circ}$ C Storage Period : 12 months max. Power Capacity : 1W max.

Part Number

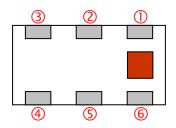
BL 1608 - 10 V 4600 KB □ /LF

① ② ③ ④ ⑤ ⑥ ⑦ ⑧

① Туре	BL : Balun	② Dimensions (L × W)	1.6 × 0.8 mm	
3 Balanced Impedance	10 : 100 ohm	Material Code	V	
© Central Frequency	4600 : 4600MHz	6 Specification Code	КВ	
7 PackagingT: Tape & ReelB: Bulk		Soldering	/LF=lead-free	



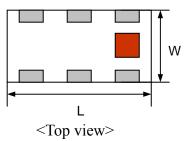
Terminal Configuration

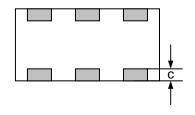


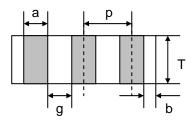
No.	Terminal Name	No.	Terminal Name	
1	Unbalanced Port	4	Balanced Port	
2	GND or	(5)	GND	
(Z)	DC feed + RF GND)	GND	
3	Balanced Port	6	NC	

Dimensions and Recommended PC Board Pattern

Unit: mm



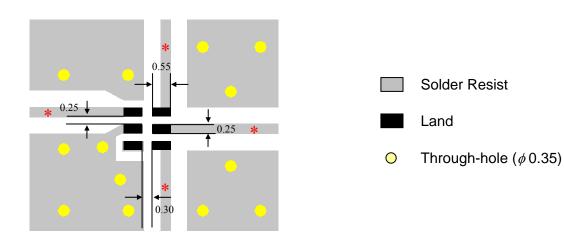




<Bottom view>

<Side view>

Mark	L	W	Т	а	b	С	g	р
Dimensions	1.6 ±	0.8 ±	0.6±	0.2 ±	0.2±	0.15 ±	0.3 ±	0.50 ±
Dilliensions	0.1	0.1	0.1	0.1	0.15	0.1	0.1	0.05

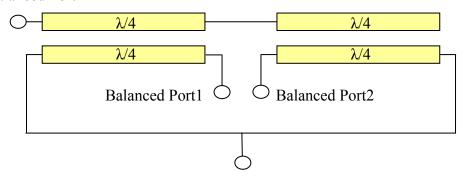


 $^{^{\}star}$ Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.



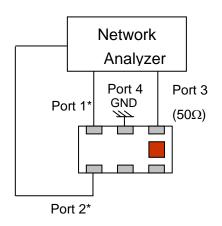
Equivalent Circuit

Unbalanced Port



Pin2(GND or DC feed + RF GND)

Measuring Diagram



Port 3:Unbalanced Port

Ports 1 and 2: Balanced Port

Ports 4: GND or DC feed + RF GND

IL=S_{ds21}

RL=S_{ss11}

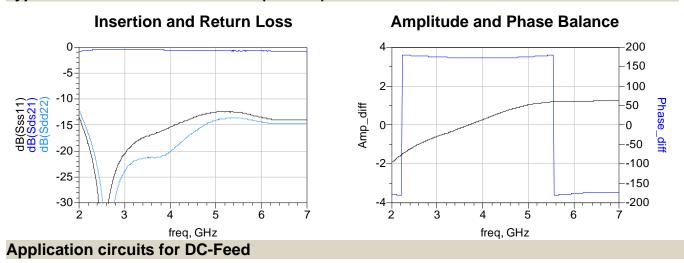
 $Amp_balance = dB(S(1,3)/S(2,3))$

Phase_balance = Phase(S(1,3)/S(2,3))

*Impedance for ports 1 and 2 = Balanced Impedance/2

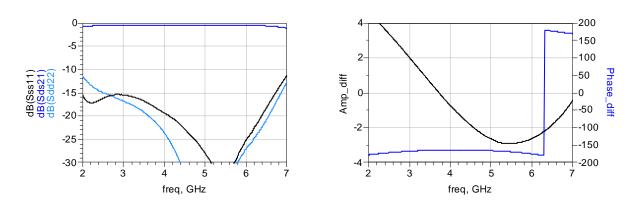


Typical Electrical Characteristics (T=25°C)



With DC feed Through-hole should be placed to capacitor as close as possible. **By-pass capacitor is recommended as 47pF (Chip Size: 0402) Solder Resist Land Through-hole (\$\phi\$ 0.3)

- *Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.
- ** By-pass capacitor should be connected when feeding DC power. The behavior of the by-pass capacitor operating at RF frequency is the electrically short to GND, when the by-pass capacitor is enough big. In generally, the better grounding is along with the better imbalance. Hence, the by-pass capacitor should be placed to the pin2 of balun as close as possible. In real case, the imbalance depends on the grounding effect of the by-pass capacitor. The following graph is the measurement result with the by-pass capacitor, the imbalance is worse than that without by-pass capacitor, and is out of spec slightly.



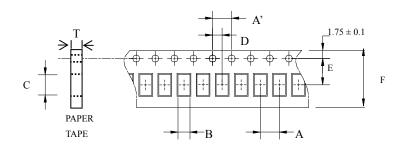
Notes

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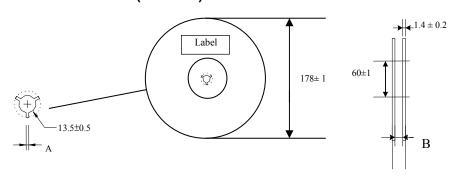
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Туре	Α	A'	В	С	D	E	F	Т	Quantity/reel	Tape material
1608	4.0±	4.0±	1.10±	1.92±	2.0±	3.5±	8.0±	0.75±	4,000pcs	Paper
1000	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.05	4,000pcs	гареі

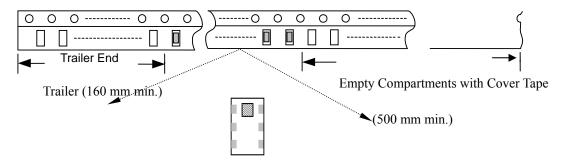
❖Reel Dimensions (Unit: mm)



Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

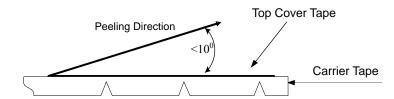
Туре	Α	В	
1608	2.3±0.5	9.0±0.3	

❖Leader and Trailer Tape





❖Peel-off Force



Peel-off force should be in the range of 0.1-0.6~N at a peel-off speed of $300\pm10~mm/min$.

❖Storage Conditions

- (1) Temperature: 5 ~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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Mechanical & Environmental Characteristics

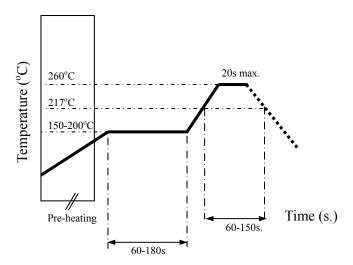
Item	Requirements	Procedure
Solderability Soldering strength (Termination Adhesion)	 No apparent damage More than 95% of the terminal electrode shall be covered with new solder 1. 10N minimum 	 Preheat: 120± 5 °C Solder: 245± 5°C for 5± 1 sec Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction.
Deflection (Substrate Bending)	No apparent damage Fulfill the electrical specification	 Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. Apply a bending force of 2mm deflection. Pressure Rod 90mm
Heat/Humidity Resistance	No apparent damage Fulfill the electrical specification after test	 Temperature: 85± 2°C Humidity: 90% ~ 95% RH Duration: 1000±48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	No apparent damage Fulfill the electrical specification after test	 One cycle/step 1 : 125 ± 5°C for 30 min step 2 : - 40 ± 5°C for 30 min No of cycles : 100 Recovery:1-2 hrs
Low Temperature Resistance	 No apparent damage Fulfill the electrical specification after test 	 Temperature: -40± 5 °C Duration: 500 ±24hrs Recovery: 1-2hrs



Soldering Conditions

❖Typical Soldering Profile for Lead-free Process

Reflow Soldering:



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